



From nature, for our future

PLANTIC™ CF



PLANTIC™ CF is a high barrier compostable barrier sealant and once laminated can be used for all pouch applications. Available to converters, processors and retailers who are looking to enhance their sustainability credentials and enhance their products by choosing PLANTIC™ CF



PLANTIC™ CF 100% compostable material

PLANTIC™ CF available as a barrier sealant

PLANTIC™ CF has an exceptionally high gas barrier, which dramatically extends the shelf life of the packaged product

PLANTIC™ CF uses up to 40% less energy compared to conventional polymers

PLANTIC™ CF significantly reduces environmental impacts being derived from plant based materials

PLANTIC™ CF laminate to paper or other compostable materials

kuraray

APPLICATIONS

PLANTIC™ CF High Barrier Sealant film is manufactured using modern technology where thin layers of Bio sourced Poly butylene Succinate (PBS) are adhered to a core layer of renewably sourced high barrier PLANTIC™ HP sheet. The PLANTIC™ HP core provides exceptional gas barrier and the BPS provides excellent heat seal ability. Both materials are compostable, providing a compostable high gas barrier sealant film for all Pouch applications.

TECHNICAL DATA

PRODUCT CHARACTERISTICS

Standard Thickness – 80 to 150 µm ± 5%*
Standard Widths – up to 960mm
Colour Range – Clear and various colour tones on request

PHYSICAL PROPERTIES

Properties	Test Method	Value	Units
Tensile Modulus	ASTM D882	1800	MPa (23°C and 50%RH)
Tensile Strength	ASTM D882	33	MPa (23°C and 50%RH)
Elongation at break	ASTM D882	50	% (23°C and 50%RH)
Impact Strength	ASTM D256	40	mN/µm (23°C and 50%RH)
Haze	ASTM F1003	<10	%
H ₂ O Transmission Rate	ASTM F1249-01	<50	g/m ² /24h @ 38°C, 90% RH
O ₂ Transmission Rate	ASTM F1927-98	<1	cm ³ /m ² /24h @ 23°C, 1atm. 100% O ₂ 50% RH

Test results for 115 µm laminated thickness

THERMAL PROPERTIES

Properties	Value	Units
Sealing temperature	105-120**	°C

* For sealing time and conditions with other films, please contact a Plantic technical representative.

**For more information on thermoforming conditions such as heating and pressures etc., please refer to the latest Plantic guidelines available from a Plantic technical representative.